

ACS257MS

Radiation Hardened Quad 2-Input Multiplexer with Three-State Outputs

November 1997

Features

- QML Qualified Per MIL-PRF-38535 Requirements
- 1.25Micron Radiation Hardened SOS CMOS
- Radiation Environment
 - Latch-up Free Under any Conditions

 - SEU LET Threshold>100MeV/(mg/cm²)
- Input Logic Levels . . .V_{IL} = (0.3)(V_{CC}), V_{IH} = (0.7)(V_{CC})
- Output Current ±8mA
- Quiescent Supply Current......400μA
- Propagation Delay
 - Enable to Output13ns
 - Input or Address to Output14ns

Applications

- 4-Bit Source Selection
- Data Routing
- High Frequency Switching

Ordering Information

Description

The Radiation Hardened ACS257MS is a Quad 2-Channel multiplexer which selects four bits of data from one of two sources under the control of a single select pin. The Output Enable input is active LOW and controls all outputs. When \overline{OE} is set HIGH, all outputs are configured into a high impedance state, regardless of all other input conditions. All inputs are buffered and the outputs are designed for balanced propagation delay and transition times.

The ACS257MS is fabricated on a CMOS Silicon on Sapphire (SOS) process, which provides an immunity to Single Event Latch-up and the capability of highly reliable performance in any radiation environment. These devices offer significant power reduction and faster performance when compared to ALSTTL types.

Specifications for Rad Hard QML devices are controlled by the Defense Supply Center in Columbus (DSCC). The SMD numbers listed below must be used when ordering.

Detailed Electrical Specifications for the ACS257 are contained in SMD 5962-98008. A "hot-link" is provided on our homepage with instructions for downloading. http://www.intersil.com/data/sm/index.htm

SMD PART NUMBER	INTERSIL PART NUMBER	TEMP. RANGE (^o C)	PACKAGE	CASE OUTLINE
5962F9800801VEC	ACS257DMSR-02	-55 to 125	16 Ld SBDIP	CDIP2-T16
N/A	ACS257D/Sample-02	25	16 Ld SBDIP	CDIP2-T16
5962F9800801VXC	ACS257KMSR-02	-55 to 125	16 Ld Flatpack	CDFP4-F16
N/A	ACS257K/Sample-02	25	16 Ld Flatpack	CDFP4-F16
N/A	ACS257HMSR-02	25	Die	N/A

Pinouts



CAUTION: These devices are sensitive to electrostatic discharge; follow proper IC Handling Procedures. 1-888-INTERSIL or 321-724-7143 | Copyright © Intersil Corporation 1999

Die Characteristics

DIE DIMENSIONS:

Size: 2390μm x 2390μm (94 mils x 94 mils) Thickness: 525μm ±25μm (20.6 mils ±1 mil) Bond Pad: 110μm x 110μm (4.3 x 4.3 mils)

METALLIZATION: AI

Metal 1 Thickness: $0.7\mu m \pm 0.1\mu m$ Metal 2 Thickness: $1.0\mu m \pm 0.1\mu m$

SUBSTRATE POTENTIAL:

Unbiased Insulator

Metallization Mask Layout

PASSIVATION

Type: Phosphorous Silicon Glass (PSG) Thickness: $1.30\mu m \pm 0.15\mu m$

SPECIAL INSTRUCTIONS:

Bond V_{CC} First

ADDITIONAL INFORMATION:

Worst Case Density: $<2.0 \times 10^5 \text{ A/cm}^2$ Transistor Count: 212



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